

## EV Group Recognized by Bosch as a Preferred Supplier of Semiconductor Equipment – February 1, 2022

# semiconductor packaging news

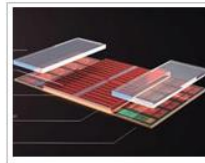
We search for industry news, so you don't need to.

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February 1, 2022

### Next-Gen 3D Chip/Packaging Race Begins

The first wave of chips is hitting the market using a technology called hybrid bonding, setting the stage for a new and competitive era of 3D-based chip products and advanced packages. AMD is the first vendor to unveil chips using copper hybrid bonding, an advanced die-stacking technology that enables next-generation 3D-like devices and packages. Hybrid bonding stacks and connects chips ...



### Semiconductor Engineering

#### Flip Chip Bonding / C4 technology

High precision process of assembly and connection technology (AVT) for contacting unhusked semiconductor chips by means of balls - so-called "bumps".



Tresky Automation

#### Ultimate Speed MRSI-H Die Bonders

Advanced 1.5 micron die bonding solution for HPLD, LDMOS & TO. Flexibility and speed for epoxy stamping & dispensing, silicon photonics, and eutectic processes.



MRSI Systems

### VIEWPOINT 2022: Ramachandran "Ram" K. Trichur, Global Market Segment Head, Henkel

In my 20 years in the semiconductor industry, I have never experienced such an intersection of demand drivers and workforce challenges as seen in late 2020 and throughout 2021. While automotive electrification, big data, mobile and 5G were all predicted to grow at a steady pace over the next several years ...



Henkel Corporation

### Critical Considerations for Electronic Component Tin Whisker Mitigation

Tin whiskers are a known reliability concern since tin whiskers are conductive. This paper discusses a more reliable method to mitigate tin whiskers via robotic hot solder dip ...

Technical Paper

### Where did it all go wrong for chipmaker Intel?

American chipmaking giant Intel is a shadow of its former self. Despite the global semiconductor shortage, which has boosted rival chipmakers, Intel is making less ...

Asia Times

### Technical Papers

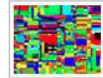
- Improving Si and SiC Wafer Dicing Yields with Thermal Laser Separation
- Critical Considerations for Electronic Component Tin Whisker Mitigation
- Why AgCoat® Prime, why now?
- The New Technology Solutions for Advanced SiP Devices
- The Effects of Long-Term Storage on Solderability of Components
- Optimizing cycle times in the semiconductor industry with Openair-Plasma
- Preparing TEM Specimens and Atom Probe Tips by Laser Machining

Optimizing cycle times with Openair-Plasma

AEC Grade-0 and MSL Level-1 Conductive Paste & Film Adhesives

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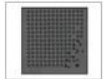
### Test Your Knowledge

What plane did Aerospatiale of France and the British Aircraft Corp. develop?

See answer below.

### Prevent Costly Die Migration.

Avoid the high costs associated with die migration from the pockets of chip trays with Gel-Pak's New LCS2™ Waffle Pack Lid.



Learn more.

Gel-Pak, a Division of Delphon

### Press Releases

#### EV Group Recognized by Bosch as a Preferred Supplier of Semiconductor Equipment

EV Group announced that it has been named a "Preferred Supplier" in the field of semiconductor by the Global Business Services Purchasing division of Robert Bosch GmbH. EVG ...

EV Group

#### Dual Gate Drivers from STMicroelectronics Optimize and Simplify SiC and IGBT Switching Circuits

Two new dual-channel galvanically-isolated gate drivers for IGBTs and silicon-carbide (SiC) MOSFETs from STMicroelectronics save space and ease circuit design in high-voltage ...

STMicroelectronics

#### SEMI Applauds House Introduction of America Competes Act of 2022 with Funding for CHIPS Act

SEMI applauded the introduction of the America Competes Act of 2022 in the United States House of Representatives. The bill includes funding for the Creating Helpful Incentives ...

SEMI

Plasma surface treatment has uses in semiconductor manufacturing, such as wire bonding, die bonding, thermal compress bonding, and pre-molding.  
**Plasmatreat GmbH**



240° Tg and ultra-high thermal stability for AEC Grade-0 applications. Proven rapid and snap curing die-attach paste for ultimate productivity.  
**AI Technology, Inc.**



#### **GlobalWafers falls short in push to save Siltronic deal**

GlobalWafers Co failed to reach a breakthrough in a last-ditch bid to salvage its planned takeover of Siltronic AG, likely spelling the collapse of the US\$5 billion deal. The ...  
**Taipei Times**

#### **China approves AMD's US\$35 billion Xilinx purchase in landmark chip deal**

Chinese regulators have granted approval for Advanced Micro Devices Inc (AMD) to buy Xilinx Inc, clearing the way for one of the largest deals to emerge from the global ...  
**Taipei Times**

#### **TSMC outlay keeps economy afloat**

Taiwan's economy is set to receive a substantial boost this year from Taiwan Semiconductor Manufacturing Co's (TSMC) unprecedented spending spree, as the chipmaking ...  
**Taipei Times**

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KYZEN offers safe, affordable alternatives that work!  
KYZEN 30  
Whole Science and Care Concepts. 1985

#### **Uneven chip supplies not necessarily all bad: Q&A with ChipMOS Technologies chair SJ Cheng**

Taiwan's semiconductor packaging and testing sector has scored its best-ever business results over the past two years, with the display driver IC (DDI) backend segment ...  
**Digitimes**

#### **TI Emphasizes Fab Investments in Earnings Report**

Texas Instrument's fourth-quarter revenue exceeded expectations, beating estimates of \$1.94 per share on \$4.4 billion in sales with profits of \$2.27 per share on \$4.83 ...  
**EE Times**

#### **Taiwan to maintain market share as chip shortage lasts through 2022**

Taiwan's share of the global semiconductor manufacturing industry is predicted to remain constant over the coming years, as a supply shortage for the critical technology ...  
**Taiwan News**

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Our PORTA-VAC and PORTA-WAND wafer wands eliminate vacuum lines. Rechargeable wands and alkaline battery powered tools are available.  
**Virtual Industries, Inc.**



New JCET Bumping Line in South Korea  
Automotive, wireless, computing and other devices have been qualified on this new 12 Inch Wafer Bumping Line which is an integral part of JCET's advanced flip chip packaging offerings.  
**JCET**



#### **Tokyo Electron brings Albany Nanotech to next level with French scientist**

If Albany Nanotech is awarded the National Semiconductor Technology Center -- a \$2 billion federal research center for computer chip manufacturing research envisioned ...  
**Times Union**

#### **Semi-automated die sort**

The DE35-ST offers a price sensitive solution for picking devices at throughputs up to 500 uph. Add options for all-die-surface inspection to ensure known good quality.  
**Royce Instruments**



#### **Quote of the Day**

"Doubt everything or believe everything: these are two equally convenient strategies. With either we dispense with the need for reflection."  
**Henri Poincare**

#### **2x Faster, 1/2 the Capital Cost, 1/2 the Footprint**

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate.  
**Yield Engineering Systems, Inc.**



#### **Epoxy for EMI/RFI Shielding**

Master Bond EP5G-80 is a one part, graphite filled epoxy paste featuring electrical and thermal conductivity that meets NASA low outgassing specifications.  
**Master Bond**



#### **What Year Was It?**

##### **Oxford Dictionary Debuts**

The first portion, or fascicle, of the Oxford English Dictionary, considered the most comprehensive and accurate dictionary of the English language, is published.  
**The day was Feb 1. What year was it?**



#### **NEW WX3000™ Metrology & Inspection Systems**

Increase throughput with the NanoResolution MRS Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour. Learn more.  
**CyberOptics Corporation**



#### **New Low Cost Plasma Desmear System**

Designed exclusively for low volume and startup PCB manufacturers, the MK-II ECO is an unbeatable value at just \$49,900. It features a 24" by 18" horizontal shelf for desmear and etch back.  
**Plasma Etch**



#### **Cartoon of the Day**




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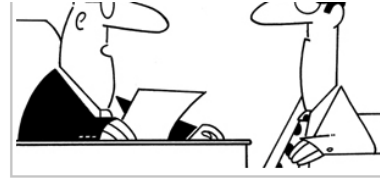
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"I'd like to give you a raise and promotion, but that wouldn't be fair to others who don't stay late or work as hard as you."  
Copyright © Randy Glasbergen

### Calendar

- [Jan 31, 2022: Pan Pacific Microelectronics Symposium](#)
- [Feb 3, 2022: Overview of Semiconductor Manufacturing webinar for American Attendees](#)
- [Feb 9, 2022: SEMICON Korea 2022 Hybrid](#)
- [Feb 10, 2022: Overview of Semiconductor Manufacturing/Santa Clara, Ca](#)

#### Have you seen wafer wands without hoses?

Our PORTA-VAC and PORTA-WAND wafer wands eliminate vacuum lines. Rechargeable wands and alkaline battery powered tools are available.



**Virtual Industries, Inc.**

#### New JCET Bumping Line in South Korea

Automotive, wireless, computing and other devices have been qualified on this new 12 Inch Wafer Bumping Line which is an integral part of JCET's advanced flip chip packaging offerings.



**JCET**

#### Die-Module Attach (Pastes & Films)

Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption-stress-free bonding.



**AI Technology, Inc.**

#### Test Your Knowledge Answer

What plane did Aerospatiale of France and the British Aircraft Corp. develop?

Answer: The Concorde

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